Customer Information Notification

201809013IU01

Issue Date: 25-Oct-2018
Effective Date: 14-Nov-2018

UPDATE

Here's your personalized quality information concerning products Digi-Key purchased from NXP.
For detailed information we invite you to view this notification online

Change Category

[ ] Wafer Fab Process	[ ] Assembly Process	[X] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[X] Electrical spec./Test coverage
[ ] Firmware	[ ] Other			

MPC5777C Marking Change and Data Sheet Updates to Rev13

Description

NXP Semiconductors announces a marking change and data sheet update for the MPC5777C from revision 11 to revision 13. Data sheet revision 12 is released in conjuction with revision 13. The revision history included in the updated document provides a details description of the changes.

Marking change and data sheet updates are summarized in the attached file with this notification.

The MPC5777C data sheet revision 13 is attached to this notice and can be found at:
https://www.nxp.com/products/processors-and-microcontrollers/power-architecture-processors/mpc5xxx-55xx-32-bit-mcus/ultra-reliable-mpc57xx-32-bit-automotive-and-industrial-microcontrollers-mcus/ultra-reliable-mpc5777c-mcu-for-automotive-industrial-engine-management:MPC5777C?tab=Documentation_Tab

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-03 and SEM-PA-13

Reason

The data sheet has been updated to provide additional technical clarification on some device features.
The addition of a 5th line of marking to expand customer part offering.

Identification of Affected Products

Top side marking
The marking for MPC5777C product family will change from 4 to 5 lines. Please refer to attachment for details.

Update Information

Updated the MPC5777C Marking Change and Data Sheet Updates_to_Rev13_DeQuMa.pdf and MPC5777C Marking Change and Data Sheet Updates_to_Rev13_DeQuMa.zip file.

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision
A new datasheet will be issued
Disposition of Old Products
Existing inventory will be shipped until depleted
Material with the additional line of marking will begin shipping January 2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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Affected Part Number

SPC5777CK2MMO3
SPC5777CCK3MME3
SPC5777CK2MME3
SPC5777CK3MMO3
SPC5775BDK3MME2
SPC5777CK3MME3
SPC5777CK3MME3
SPC5775EDK3MME3
SPC5777CK3MMO3